

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Joseph E. Geusic et al.

Title: INTEGRATED CIRCUITS USING OPTICAL FIBER INTERCONNECTS FORMED
THROUGH A SEMICONDUCTOR WAFER

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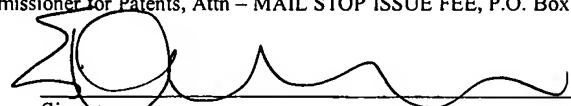
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